

Compound Semiconductor Market Size Expected to Grow from USD 42.86 Billion in 2026 to USD 117.92 Billion by 2035

Compound Semiconductor Market Size, Share and Research Report: By Application (Telecommunications, Consumer Electronics, Lighting, Automotive, Renewable Energy)

TOKYO, TOKYO, JAPAN, August 25, 2026

/EINPresswire.com/ -- The Global [compound semiconductor market](#) reached an estimated USD 38.47 billion in 2025 and is projected to grow from USD 42.86 billion in 2026 to USD 117.92 billion by 2035, registering a CAGR of 7.91% during the forecast

period. Two major catalysts are accelerating this trajectory: the explosive global rollout of 5G network infrastructure requiring gallium nitride (GaN) and gallium arsenide (GaAs) power amplifiers operating at millimeter-wave frequencies, and the [electric vehicle \(EV\)](#) revolution driving unprecedented demand for silicon carbide (SiC) and GaN power electronics capable of delivering the switching speed and thermal efficiency that silicon-based devices fundamentally cannot match. With global semiconductor capital expenditure projected to exceed USD 600 billion through 2030, compound semiconductor fabs and epitaxial wafer suppliers find themselves at the epicenter of the most consequential materials transition in electronics history.

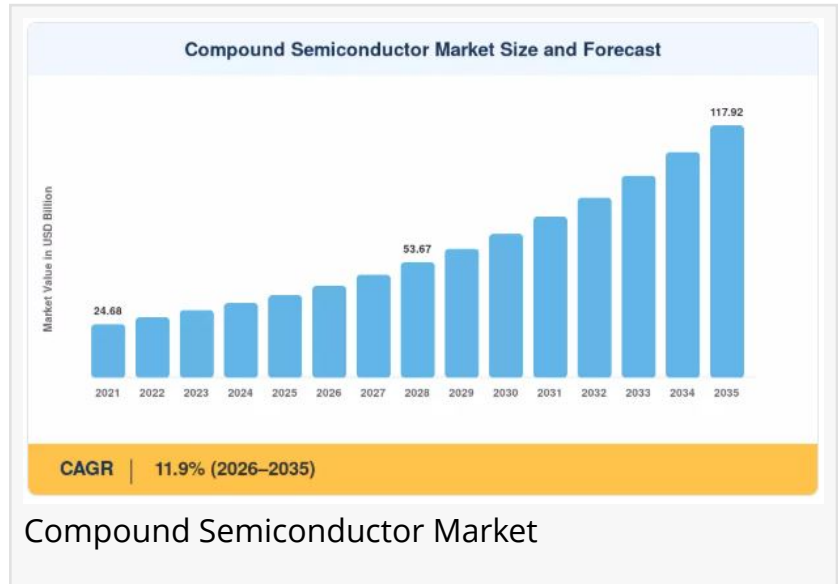
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Compound Semiconductor Market is advancing with rising demand for high-performance materials in 5G, electric vehicles, aerospace, and renewable energy applications.”

Market Research Future (MRFR)

Legacy silicon-based power devices long dominant across consumer electronics and industrial motor drives are rapidly yielding ground to III-V and IV-IV compound semiconductor platforms that integrate wide-bandgap

properties, superior electron mobility, and radiation hardness. A recent McKinsey semiconductor practice analysis estimated that automotive OEMs adopting SiC-based inverter modules in EV



drivetrains achieved 5–8% improvements in driving range per charge cycle versus silicon IGBT alternatives, a performance delta that is proving decisive in the competitive EV market. This technology transition is not incremental it represents a foundational restructuring of the global semiconductor supply chain.

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□ How Significant Is the Compound Semiconductor Market's Growth?

The compound semiconductor market has demonstrated exceptional and accelerating expansion, rising from approximately USD 32.1 billion in 2021 to an estimated USD 38.47 billion in 2025, representing a strong historical growth trajectory underpinned by secular demand from [5G infrastructure](#), defense electronics, photonics, and automotive electrification. The market is expected to more than double over the next decade, driven by the convergence of multiple high-growth end-markets simultaneously adopting compound semiconductor solutions as the only viable path to achieving their performance objectives.

Surging EV production volumes, explosive data center power density growth, the proliferation of LiDAR and photonic sensors in autonomous vehicles, and the expanding deployment of satellite constellations in low-Earth orbit (LEO) have collectively created an acute demand environment for GaAs, GaN, SiC, indium phosphide (InP), and gallium antimonide (GaSb) compound materials. Defense agencies across the United States, Europe, and Asia-Pacific are also accelerating compound semiconductor procurement for radar, electronic warfare, directed-energy weapons, and secure optical communications systems adding a strategically critical and budget-insulated demand stream to the market's growth equation.

□ What Does the Future Hold for the Compound Semiconductor Market?

Wide-bandgap (WBG) semiconductor materials particularly gallium nitride and silicon carbide stand at the absolute forefront of the market's next growth phase. GaN-on-SiC transistors are enabling the base station power amplifiers that make millimeter-wave 5G commercially viable, while SiC MOSFETs are being designed into EV traction inverters, onboard chargers, and DC fast-charging infrastructure at a rate that has left SiC wafer suppliers scrambling to expand capacity. Ultra-wide-bandgap (UWBG) materials including gallium oxide (Ga₂O₃) and aluminum nitride (AlN) are emerging from research labs with theoretical breakdown voltages that could make even WBG devices look conservative by the 2030s.

The photonics revolution represents another defining force reshaping the market's future. Indium phosphide-based photonic integrated circuits (PICs) are becoming the backbone of 800G and 1.6T optical transceiver modules demanded by hyperscale data centers, while vertical-cavity surface-emitting lasers (VCSELs) fabricated on GaAs substrates are proliferating across 3D sensing, LiDAR, and industrial machine vision applications. The integration of III-V photonic

components with silicon photonics platforms heterogeneous integration is expected to unlock a new wave of co-packaged optics (CPO) products that will reshape data center networking architecture through 2035.

Geopolitical pressures are equally shaping the market's structural future. The CHIPS and Science Act in the United States, the European Chips Act, and parallel industrial policy initiatives across Japan, South Korea, and India are directing tens of billions in public investment toward domestic compound semiconductor manufacturing capacity fundamentally altering where these critical materials are produced and creating new regional supply chain dynamics that will define market geography through the next decade.

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□ Who Are the Key Players in the Compound Semiconductor Market?

The compound semiconductor landscape is characterized by a mix of vertically integrated device manufacturers, pure-play epitaxial wafer suppliers, specialized foundry services, and diversified semiconductor conglomerates. Key participants shaping the competitive dynamics include:

Wolfspeed (formerly Cree) — the world's largest dedicated SiC power device and wafer manufacturer, supplying automotive and industrial markets globally

II-VI Incorporated (Coherent Corp.) — delivering compound semiconductor wafers, epitaxial products, and photonic devices across communications, industrial, and defense segments

Qorvo — providing GaAs and GaN RF solutions for mobile, infrastructure, defense, and Wi-Fi applications

Skyworks Solutions — supplying GaAs-based RF semiconductor solutions predominantly for smartphone and IoT connectivity markets

Broadcom Inc. — producing GaAs power amplifiers and optical components serving mobile, data center, and broadband infrastructure

onsemi (formerly ON Semiconductor) — offering SiC power modules and discrete devices for EV, industrial, and energy applications

STMicroelectronics — providing SiC MOSFETs and diodes targeted at automotive and industrial power conversion markets

MACOM Technology Solutions — delivering GaAs, GaN, and InP semiconductor products for optical, microwave, and millimeter-wave applications

IQE plc — the leading independent epiwafer supplier for GaAs, InP, GaN, and other compound semiconductor materials globally

Infineon Technologies — offering SiC and GaN power semiconductors for automotive, industrial, and renewable energy applications

Competition in the market is intensifying as incumbent device makers race to secure long-term SiC and GaN wafer supply through vertical integration and strategic supply agreements with substrate manufacturers. Simultaneously, new entrants from China supported by substantial state investment are aggressively expanding domestic compound semiconductor capabilities in GaN-on-Si power devices and SiC substrates, fundamentally challenging the geographic concentration of existing supply chains.

□ What Are the Emerging Trends in the Compound Semiconductor Market?

Several transformational trends are redefining how the compound semiconductor market evolves through 2035:

GaN-on-Si Cost Reduction: The migration of GaN epitaxy onto large-diameter silicon substrates (200mm and 300mm) is dramatically reducing the cost of GaN power devices, enabling mass-market adoption in consumer fast chargers, data center power supplies, and automotive auxiliary systems.

SiC Wafer Capacity Race: Global SiC substrate supply remains critically constrained relative to automotive demand forecasts. Major OEMs including Tesla, BYD, and BMW are entering direct long-term supply agreements with SiC wafer producers a procurement model previously unseen in the semiconductor industry.

Heterogeneous Integration & Chiplets: The co-integration of III-V compound semiconductor dies with silicon logic in advanced packaging formats (2.5D, 3D stacking, chiplets) is unlocking unprecedented performance density in data center ASICs, RF front-end modules, and photonic computing platforms.

LEO Satellite & Space Photonics: The exponential growth of LEO satellite constellations (SpaceX Starlink, Amazon Kuiper, OneWeb) is driving substantial demand for radiation-hardened InP-based laser arrays, GaAs solar cells, and GaN power amplifiers qualified for space environments.

Gallium Oxide (Ga₂O₃) Commercialization: Ultra-wide-bandgap Ga₂O₃ devices are transitioning from academic research to early commercial demonstration, with several startups and national labs targeting power electronics applications that could eventually challenge SiC and GaN in high-voltage regimes above 10 kV.

Supply Chain Nationalization: Export controls on compound semiconductor materials, equipment, and technology between the U.S., China, Japan, and the Netherlands are accelerating domestic industrial policy investments and reshaping the global supply chain into increasingly regionalized blocs.

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□ How Is the Compound Semiconductor Market Segmented?

The compound semiconductor market report provides a comprehensive segmentation framework:

- 1 By Material Type: Gallium Arsenide (GaAs), Gallium Nitride (GaN), Silicon Carbide (SiC), Indium Phosphide (InP), Gallium Antimonide (GaSb), Others
- 2 By Device Type: Power Devices, RF Devices, Optoelectronics (LEDs, Lasers, Photodetectors), Transistors, Diodes
- 3 By Wafer Size: 2-inch, 4-inch, 6-inch, 8-inch and Above
- 4 By End-Use Vertical: Telecommunications & 5G, Automotive & EV, Aerospace & Defense, Consumer Electronics, Industrial, Data Centers & Optical Communications, Renewable Energy
- 5 By Organization Size: Fabless Design Companies, Integrated Device Manufacturers (IDMs), Pure-Play Foundries

□ What Are the Regional Insights from the Compound Semiconductor Market?

North America commands approximately 36% of global compound semiconductor market share, underpinned by the United States' dominant position in GaN defense electronics, the world's most advanced compound semiconductor research ecosystem, and a rapidly expanding domestic SiC manufacturing base anchored by Wolfspeed's multi-billion-dollar fab investments in North Carolina and New York. The CHIPS and Science Act's targeted compound semiconductor provisions are expected to sustain and deepen the region's technological leadership through the forecast period.

Europe holds the second-largest share at approximately 24%, with Germany, the United Kingdom, Sweden, and the Netherlands home to critical compound semiconductor research centers, specialty foundries, and device manufacturers. The European Chips Act is directing €43 billion in public and private investment toward semiconductor self-sufficiency — with compound semiconductors for automotive (SiC), 5G (GaN), and photonics (InP) designated as strategic priority technologies. STMicroelectronics and Infineon have both announced major SiC capacity expansions in Europe in response.

Asia-Pacific represents the largest and fastest-growing regional market by volume, accounting for

roughly 31% of global revenues. Japan (Rohm, Mitsubishi Electric, SUMCO), South Korea (Samsung, SK Siltron), Taiwan (WIN Semiconductors, TSMC compound semiconductor operations), and China collectively host the broadest concentration of compound semiconductor manufacturing capacity in the world. China's government-directed investment in domestic SiC and GaN capabilities is particularly accelerating with the stated goal of reducing dependence on Western compound semiconductor supply chains before 2030.

Middle East & Africa is projected to register solid growth through 2035, primarily driven by defense modernization programs, 5G infrastructure build-outs, and sovereign wealth fund-backed investments in semiconductor industrial policy particularly in Saudi Arabia and the UAE, both of which have announced ambitions to develop domestic semiconductor design and manufacturing capabilities as part of broader economic diversification strategies.

South America rounds out the global picture, with Brazil and Mexico representing the most active markets for compound semiconductor device procurement in telecommunications infrastructure, renewable energy inverters, and industrial automation sectors where GaN and SiC adoption is accelerating in line with global trends.

□□□ Industry Analysis Reports by Market Research Future:

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